HEWLETT-PACKARD COMPANY
Intellectual Property Administration
P. O. Box 272400
Fort Collins, Colorado 80527-2400

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AF 2812

PATENT APPLICATION

ATTORNEY DOCKET NO. 100110412-1

IN THE
UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor(s): DODD, SIMON

Confirmation No.: 9553

Application No.: 10/055,161

Examiner: LATTIN, C.W.

Filing Date: Oct 26, 2001

Group Art Unit: 2812

Title: DEVICES AND METHODS FOR INTEGRATED CIRCUIT MANUFACTURING

Commissioner for Patents
PO Box 1450
Alexandria, VA 22313-1450

TRANSMITTAL LETTER FOR RESPONSE/AMENDMENT

Sir:

Transmitted herewith is/are the following in the above-identified application:

(X) Response/Amendment
( ) New fee as calculated below
( ) No additional fee (Address envelope to "Mail Stop Non-Fee Amendment")
( ) Other: _____ (fee $_____)
( ) Petition to extend time to respond
( ) Supplemental Declaration

CLAIMS AS AMENDED BY OTHER THAN A SMALL ENTITY						
(1) FOR	(2) CLAIMS REMAINING AFTER AMENDMENT	(3) NUMBER EXTRA	(4) HIGHEST NUMBER PREVIOUSLY PAID FOR	(5) PRESENT EXTRA	(6) RATE	(7) ADDITIONAL FEES
TOTAL CLAIMS	**6**	MINUS	**22**	= **0**	X **$18**	**$ 0**
INDEP. CLAIMS	**1**	MINUS	**7**	= **0**	X **$84**	**$ 0**
[ ] FIRST PRESENTATION OF A MULTIPLE DEPENDENT CLAIM					+ **$280**	**$ 0**
EXTENSION FEE	1ST MONTH $110.00 [ ]	2ND MONTH $410.00 [ ]	3RD MONTH $930.00 [ ]	4TH MONTH $1450.00 [ ]		**$ 0**
					OTHER FEES	$
					TOTAL ADDITIONAL FEE FOR THIS AMENDMENT	**$ 0**

Charge $ **0** to Deposit Account 08-2025. At any time during the pendency of this application, please charge any fees required or credit any overpayment to Deposit Account 08-2025 pursuant to 37 CFR 1.25. Additionally please charge any fees to Deposit Account 08-2025 under 37 CFR 1.16 through 1.21 inclusive, and any other sections in Title 37 of the Code of Federal Regulations that may regulate fees. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

DODD, SIMON

By _____

Peter Reitan

Attorney/Agent for Applicant(s)
Reg. No. **48,603**

Date: **Jul 3, 2003**

Telephone No.: **(949) 640-6200**

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, Alexandria, VA 22313-1450.

Date of Deposit: **Jul 3, 2003**

Typed Name: **Colette Angle-Olson**

Signature: Colette Angle-Olson

Rev 05/03 (TransAmd)

- Attach as First Page to Transmitted Papers -

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:	
DODD et al.	
Serial No.: 10/055,161	Group Art Unit: 2812
Filed: 10/26/2001	Examiner: LATTIN, C. W.
For: DEVICES AND METHODS FOR INTEGRATED CIRCUIT MANUFACTURING	

RESPONSE TO FINAL REJECTION (37 CFR 1.116(b))

Commissioner for Patents
PO Box 1450
Alexandria, VA 22313-1450

Sir:

This is in response to an office action mailed May 22, 2003 in the above-referenced application and to a telephone message left by Examiner Lattin on July 2, 2003.

IN THE CLAIMS

Please cancel Claims 14-20, 23-31 and 33-35 without prejudice.

Please amend Claim 32 to read as follows:

32. (Amended) A process of making a multi-layered integrated circuit, comprising the steps of:

forming, at a surface of a semiconductor die, at least an insulating layer;